

IN THE CLAIMS:

1. (previously presented) An electronic package comprising:

a circuit board;

a compressible capsule layer encasing said circuit board and in intimate contact therewith, thereby forming a sealed immersible electronic module; and

a housing receiving an outer surface of and press fit to said encapsulated electronic module and forming a protective shell around said electronic module with press fit engagement.
2. (original) An electronic package in accordance with claim 1 wherein said circuit board includes at least one sensor coupled thereto.
3. (original) An electronic package in accordance with claim 2 wherein said sensor is a hall effect sensor.
4. (previously presented) An electronic package in accordance with claim 1 wherein said compressible capsule layer comprises a melt processible rubber.
5. (previously presented) An electronic package in accordance with claim 1 wherein said housing comprises a longitudinal axis and an elongated opening extending transverse to said longitudinal axis for adjusting a position of said housing.
6. (previously presented) An electronic package in accordance with claim 1 wherein said housing comprises a mounting stud.
7. (previously presented) An electronic package in accordance with claim 1, wherein said housing comprises at least one indicator bar.

8. (previously presented) An electronic package in accordance with claim 1 wherein one of said capsule layer and said housing comprises a latch configured to engage the other of said capsule layer and said housing.

9. (previously presented) An electronic package in accordance with claim 1 further comprising a magnetic plate, said magnetic plate positioned beneath said circuit board and encased in said capsule layer.

10 - 25. (cancelled)